

PacLine 200/300

Electroless Bumping Line for **Al** and **Cu** Pad

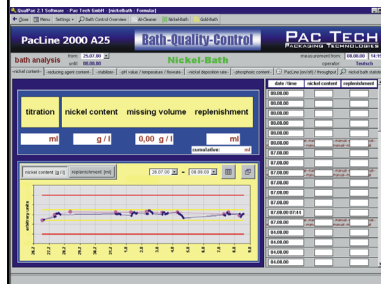


Electroless Ni/Au & Ni/Pd/Au Bumping is the Solution for Low Cost High Volume Wafer Bumping

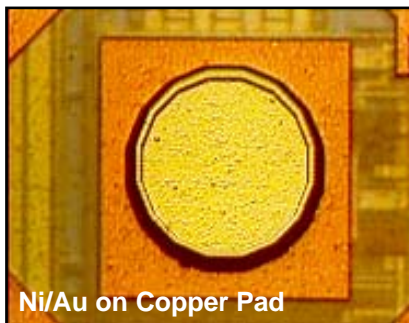
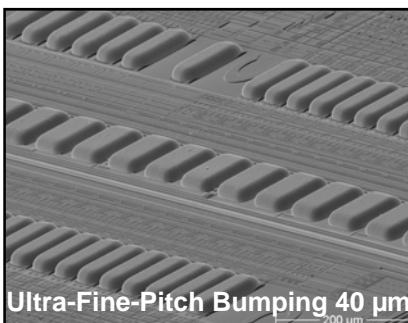
- UPH: 600.000 wafer per year (8")
- Maximum Flexibility: 6", 8", 12"
- No Tooling
- In-line Bath Control and Replenishment
- Total Quality Software QualPac 2.0
- SECS GEM Interface
- Turnkey Process Solution
- Already installed at leading OEM production sites
- Compliant with Semi S2 and FM 4910



PacLine 300 A50



QualPac – Process Control



▪ The Electroless Bumping Process is suitable for all State of the Art Flip Chip Processes:

- Soldering •NCP
- ACF •ICA

Pac Tech GmbH
Am Schlangenhorst 15-17
14641 Nauen
Germany

Tel: +49 (0)3321-4495-100
Fax: +49 (0)3321-4495-110
Email: sales@pactech.de

Pac Tech USA Inc.
328 Martin Avenue
Santa Clara, CA 95050
USA

Tel: +1 408-588-1925
Fax: +1 408-588-1927
Email: sales@pactech-usa.com

Pac Tech Asia Sdn. Bhd.
Plot 14, Medan Bayan Lepas
Technoplex, Phase 4
Bayan Lepas Industrial Zone
1190 Bayan Lepas, Penang
Malaysia

Tel: +60 19 47 83 760
Email: sales@pactech-asia.com

Pac Tech Thailand (Service Center)
98/286 Moo 9
Romruengarden vill Sol 5
Chiangragnoi, Ayutthaya 13160
Thailand

Tel: +66 899275852
Fax: +66 357422768
Email: customer.service@pactech-asia.com